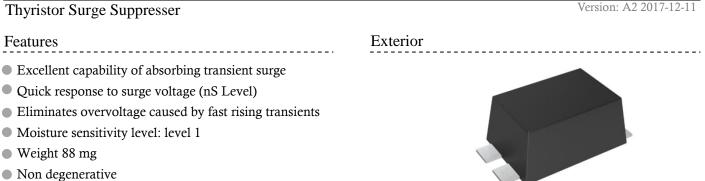


BS0300N-2C

Order Code: BS0300N-2C

Version: A2 2017-12-11



SMB-T

Application Information

RS485/232/422

Bi-directional

Package (top view)

Schematic Symbol

2

	B03N2C	1
2	1309	3

Agency Approvals _____

Icon	Description
RoHS	Compliance with 2011/65/EU
HF	Compliance with IEC61249-2-21:2003

Part Number and Electrical Parameter

	Idrm@) Vdrm	Vs ¹	@ Is	VT	ŊIт	Ін	Co ²
Part Number	μΑ	V	V	mA	V	А	mA	pF
	MAX	Pin1,3-2	Pin1,3-2		MAX		MIN	MAX
BS0300N-2C	5	25	40	800	4	2.2	50	100

Absolute maximum ratings measured at $T_A = 25^{\circ}C RH = 45\%-75\%$ (unless otherwise noted).

(1) Vs is measured at 100KV/S

(2) Off-state Capacitance is measured at VDC=2V, VRMS=1V, f=1MHz



Part Numbering System

BS	0300	Ν	2	С
(1)	(2)	(3)	(4)	(5)

- (1) Bencent Semiconductor Surge Arrester
- (2) Off state Voltage, e.g: $0300 = 30 \times 10^{0} = 30$ V.
- (3) Package: SMB-T
- (4) 2 Lines Protection
- (5) Rating Surge Voltage: 6KV (10/700µS)

V-I Curve

Parameters	Definition	
Vdrm	Peak Off-state Voltage	
Idrm	Off-state Current	
Vs	Switching Voltage	
Is	Switching Current	
Ін	Holding Current	
VT	On-state Voltage	
Іт	On-state Current	
Со	Off-state Capacitance	

+ T Idrm Î Ť VDRM Vт

Surge Ratings

	1	1	1		1
Current Waveform	2/10µs	8/20µs	10/160µs	5/320µs*	10/1000µs
Voltage Waveform	2/10µs	1.2/50µs	10/160µs	10/700µs*	10/1000µs
Ipp	500A	400A	200A	150A	100A

-Peak pulse current rating (I_{PP}) is repetitive and guaranteed for the life of the product;

-Bencent only makes the test for 5/320µs@150A* (10/700µs@6KV), but for other IPP value derived from experience is just for reference only. Bencent will not take any obligation for these parameters, so before applying our parts, please make sure to verify the parameters listed in the above table.

Thermal Considerations

Symbol	Parameter	Value	Unit
Tı	Operating Junction Temperature Range	-40 to +150	°C
Ts	Storage Temperature Range	-60 to +150	°C

Physical Characteristics

Lead Material	Copper Alloy
Body Material	UL recognized epoxy meeting flammability classification 94V-0
Terminal Finish	100% Matte-Tin Plated

Order Code: BS0300N-2C

Mark

Version: A2 2017-12-11

BS0300N-2C



B03N2C: Part Number 1309: September, 2013

www.bencent.com.cn 2/5

Specifications are subject to change without notice.

Customers should verify actual device performance in their specific applications

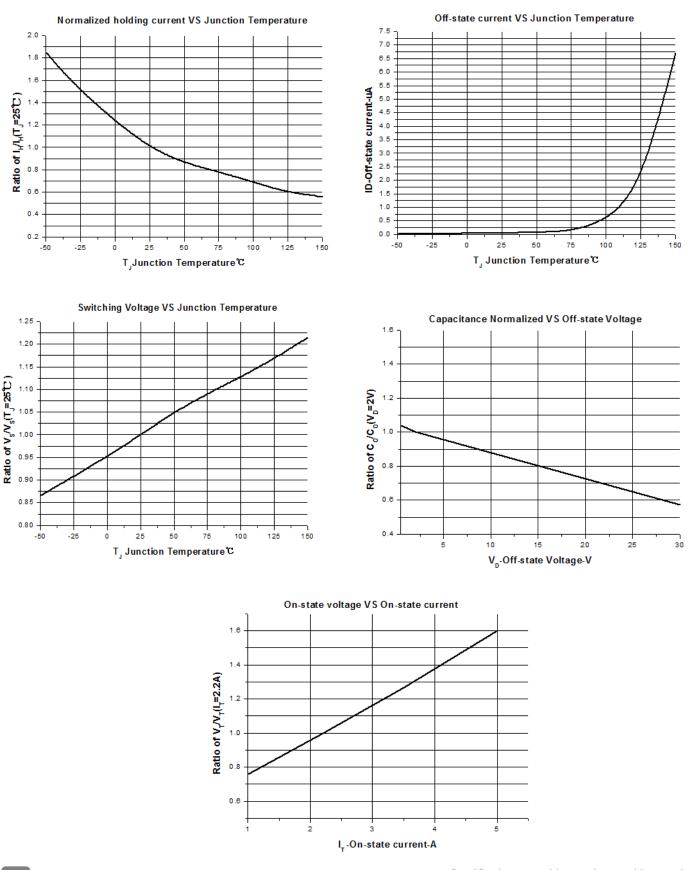


Typical Characteristics

BS0300N-2C

Order Code: BS0300N-2C

Version: A2 2017-12-11



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Environmental Characteristics

BS0300N-2C

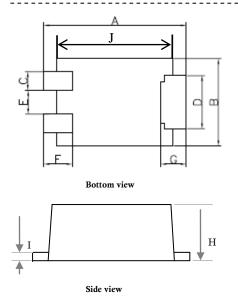
Order Code: BS0300N-2C

Version: A2 2017-12-11

Testing Items	Technical Standards
High Temperature Reverse Bias Test	Temperature: 150±3°С, Bias=80%V _{DRM} Time: 168H
High Temperature Life Test	Temperature: 150℃ Time: 168H
High-low Temperature Cycle Test	Temperature: From -40℃ to125℃ Dwell time: 30min, 10-100 cycles
High Temperature &High Humidity Test	Temperature: 85°C Humidity: 85% Test time: 168H
Pressure Cooker Test	Temperature: 121°C, 2atm. Humidity: 100% Test time: 24H to 168H
Resistance of Soldering Heat	Temperature: 260±5°C Time of dip soldering: 10s, 3times

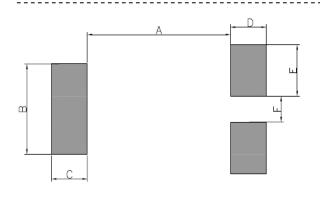
Note: The above testing items can be specified by customers by contacting Bencent service

Product Dimensions



REF	mm	inch
А	5.4±0.3	0.213±0.012
В	3.3±0.3	0.130±0.012
С	0.7±0.1	0.028 ± 0.004
D	2.0±0.2	0.079±0.008
Е	0.9±0.2	0.035±0.008
F	0.85±0.3	0.033±0.012
G	0.9±0.3	0.035±0.012
Н	2±0.3	0.079±0.012
Ι	0.25 ± 0.05	0.010±0.002
J	4.4±0.2	0.173±0.008

Recommended Soldering Pad



REF	mm	inch
А	3.4	0.134
В	2.5	0.098
С	1.6	0.059
D	1.8	0.059
Е	0.9	0.035
F	0.8	0.032

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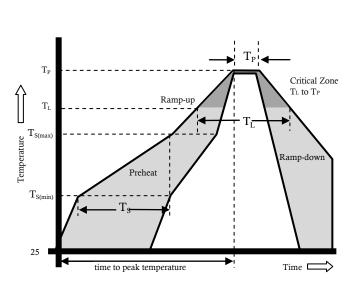


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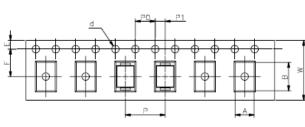


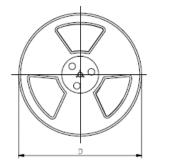
Reflow Profile

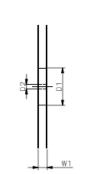
Reflow Condition			Pb-Free Assembly	
	Te	emperature Min.	+150°C	
Pre Heat	Te	emperature Max.	+200°C	
	Ti	me (Min to Max)	60 – 180 secs.	
Average ramp up rate (Liquidus Temp (T _L) to peak)			3°C/sec. Max.	
Ts(max) to	Τl・	Ramp-up Rate	3°C/sec. Max.	
Reflow	- Temperature (T _L) (Liquidus)		+217°C	
		- Temperature (T_L)	60 – 150 secs.	
Peak Temp) (T ₁	»)	+(260+0/-5)°C	
Time within 5°C of actual Peak Temp (T_P)			8 – 15 secs.	
Ramp-down Rate			6°C/sec. Max.	
Time 25°C to peak Temp (T_P)			8 min. Max.	
Do not exceed			+260°C	



Package Reel Information







REF	mm	inch	
А	3.65+/-0.3	0.144+/-0.012	
В	5.69+/-0.3	0.244+/0012	
d	1.5+/-0.1	0.059+/-0.004	
D	330.0	13.0	
D1	100+/-3	3.937+/-0.118	
D2	13+/-0.3	0.512+/-0.012	
Е	1.5+/-0.2	0.059+/-0.008	
F	5.65+/-0.2	0.222+/-0.008	
Р	8.0+/-0.2	0.315+/-0.008	
P0	4.0+/-0.2	0.157+/-0.008	
P1	2.0+/-0.2	0.079+/-0.008	
W	12.0+/-0.2	0.472+/-0.008	
W1	16.8+/-2.0	0.661+/-0.079	

Outline	Reel	Per Carton	Reel Diameters	Carton Size(mm)		
	(pcs)	(pcs)	(mm)	L	W	Η
Taping	3,000	48,000	330	360	360	385

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BS0300N-2C

Order Code: BS0300N-2C

Version: A2 2017-12-11